

Gap Filler 1500LV (Two-Part)

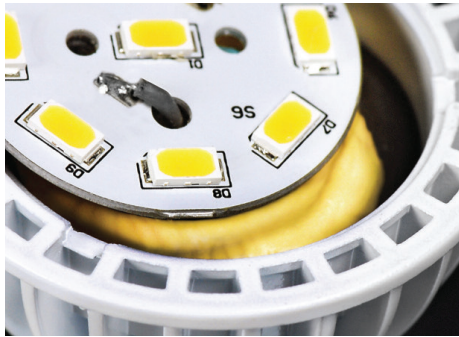
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PRODUCT DESCRIPTION

Thermally Conductive, Liquid Gap Filler Material

FEATURES AND BENEFITS

- Thermal Conductivity: 1.8 W/m-K
- Low volatility for silicone sensitive applications
- Ultra-conforming, with excellent wet-out
- 100% solids — no cure by-products
- Excellent low and high temperature chemical and mechanical stability



Gap Filler 1500LV is a two-part, high performance, thermally conductive, liquid gap filling material. This material offers the high temperature resistance and low modulus of a silicone material with significantly lower levels of silicone outgassing for use in silicone sensitive applications.

The mixed material will cure at room temperature and can be accelerated with the addition of heat. As cured, Gap Filler 1500LV provides a soft, thermally conductive, form-in-place elastomer that is ideal for fragile assemblies or for filling unique and intricate air voids and gaps.

Liquid dispensed thermal materials offer infinite thickness variations and impart little to no stress on sensitive components during assembly. Gap Filler 1500LV exhibits low level natural tack characteristics and is intended for use in applications where a strong structural bond is not required.

Note: To build a part number, visit our website at www.bergquistcompany.com.

TYPICAL PROPERTIES OF GAP FILLER 1500LV

PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD
Color / Part A	Yellow	Yellow	Visual
Color / Part B	White	White	Visual
Viscosity, High Shear (Pa-s) (1)	20	20	ASTM D5099
Density (g/cc)	2.7	2.7	ASTM D792
Mix Ratio	1:1	1:1	—
Shelf Life @ 25°C (months)	6	6	—
PROPERTY AS CURED			
Color	Yellow	Yellow	Visual
Hardness (Shore 00) (2)	80	80	ASTM D2240
Heat Capacity (J/g-K)	1.0	1.0	ASTM D1269
Siloxane Content, ΣD ₄ -D ₁₀ (ppm)	<100	<100	—
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	—
ELECTRICAL AS CURED			
Dielectric Strength (V/mil)	400	400	ASTM D149
Dielectric Constant (1000 Hz)	6.2	6.2	ASTM D150
Volume Resistivity (Ohm-meter)	10 ¹⁰	10 ¹⁰	ASTM D257
Flame Rating	V-0	V-0	U.L. 94
THERMAL AS CURED			
Thermal Conductivity (W/m-K)	1.8	1.8	ASTM D5470
CURE SCHEDULE			
Working Time @ 25°C (3)	120 min (2 hrs)	120 min (2 hrs)	—
Cure @ 25°C (hrs) (3)	8	8	—
Cure @ 100°C (min) (3)	10	10	—
1) Capillary Viscosity, 3000/sec, Part A and B measured separately. 2) Thirty second delay value Shore 00 hardness scale. 3) Parallel plate rheometer, see reactivity application note.			

TYPICAL APPLICATIONS INCLUDE

- Lighting
- Automotive electronics
- Silicone sensitive applications

CONFIGURATIONS AVAILABLE

- Supplied in cartridge and kit form

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